

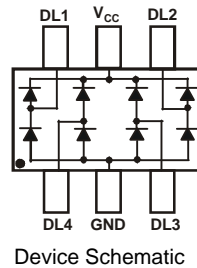
## QUAD DATA LINE SCHOTTKY BUS TERMINATOR

### Features

- Low Forward Voltage Drop
- Fast Switching
- Very High Density
- Ultra-Small Surface Mount Package PN Junction Guard Ring for Transient and ESD Protection
- Provide Transient Protection for High-Speed Data Lines in Accordance With:  
IEC61000-4-2 (ESD) 15kV (Air), 8kV (Contact)  
IEC61000-4-4 (EFT) 80A (tp = 5/50 ns)  
IEC61000-4-5 (Lightning) Class 3
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Notes 3 & 4)**

### Mechanical Data

- Case: SOT363
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe). Solderable per MIL-STD-202, Method 208
- Polarity: See Diagram
- Weight: 0.006 grams (approximate)

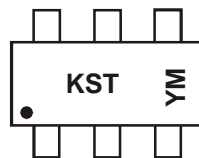


### Ordering Information (Note 5)

Part Number	Case	Packaging
QSBT40-7-F	SOT363	3000/Tape & Reel
QSBT40-13-F	SOT363	10000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See <http://www.diodes.com> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.
  5. For packaging details, go to our website at <http://www.diodes.com>.

### Marking Information



KST = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: N = 2002)  
 M = Month (ex: 9 = September)

#### Date Code Key

Year	2001	2002	2003	2004	...	2011	2012	2013	2014	2015	2016	2017
Code	M	N	P	R	...	Y	Z	A	B	C	D	E
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

### Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	30	V
Working Peak Reverse Voltage	V <sub>RWM</sub>		
DC Blocking Voltage	V <sub>R</sub>		
Forward Continuous Current (Note 6)	I <sub>FM</sub>	200	mA
Non-Repetitive Peak Forward Surge Current @ t < 1.0s	I <sub>FSM</sub>	600	mA

### Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P <sub>D</sub>	200	mW
Thermal Resistance Junction to Ambient Air (Note 6)	R <sub>θJA</sub>	625	°C/W
Operating Temperature Range	T <sub>J</sub>	-55 to +125	°C
Storage Temperature Range	T <sub>STG</sub>	-65 to +125	°C

### Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition			
Reverse Breakdown Voltage (Note 7)	V <sub>(BR)R</sub>	30	—	—	V	I <sub>R</sub> = 100μA			
Forward Voltage	V <sub>F</sub>	—	—	280	mV	I <sub>F</sub> = 0.1mA, tp < 300μS			
				350			I <sub>F</sub> = 1.0mA, tp < 300μS		
				450				I <sub>F</sub> = 10mA, tp < 300μS	
				550					I <sub>F</sub> = 30mA, tp < 300μS
				1000					
Reverse Current (Note 7)	I <sub>R</sub>	—	—	2	μA	V <sub>R</sub> = 25V			
Total Capacitance	C <sub>T</sub>	—	10.0	—	pF	V <sub>R</sub> = 0, f = 1.0MHz (Note 8)			
			6.5			V <sub>R</sub> = 0, f = 1.0MHz (Note 9)			
Reverse Recovery Time	t <sub>rr</sub>	—	—	5.0	ns	I <sub>F</sub> = I <sub>R</sub> = 10mA, I <sub>rr</sub> = 0.1 x I <sub>R</sub> , R <sub>L</sub> = 100Ω			

- Notes:
6. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com>.
  7. Short duration pulse test used to minimize self-heating effect.
  8. At V<sub>R</sub> = 0V, DL(X) to V<sub>CC</sub> or GND.
  9. At V<sub>R</sub> = 0V, between Data Lines (e.g., DL1 and DL4).

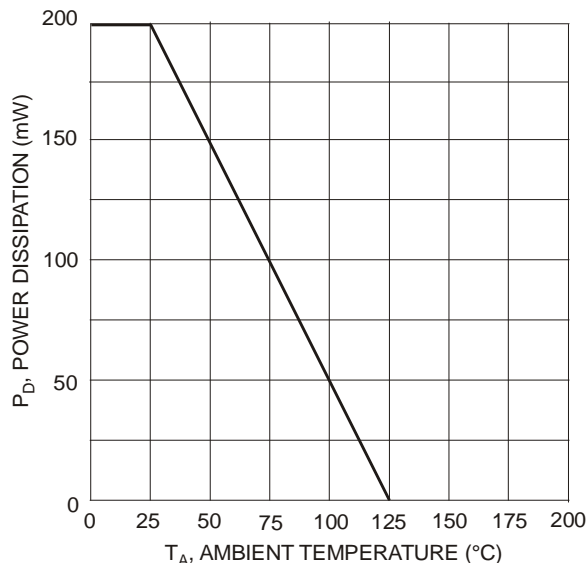
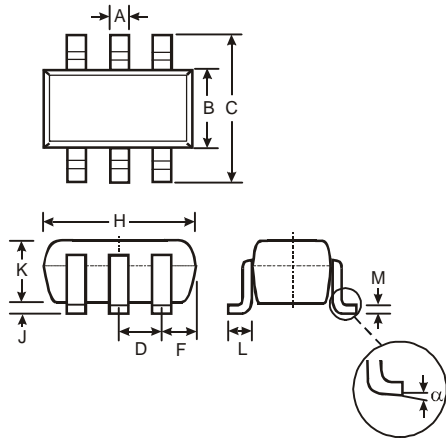


Fig. 1 Max Power Dissipation vs. Ambient Temperature

**Package Outline Dimensions**

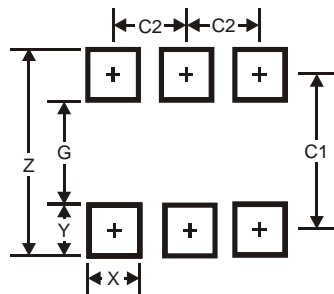
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOT363			
Dim	Min	Max	Typ
A	0.10	0.30	0.25
B	1.15	1.35	1.30
C	2.00	2.20	2.10
D	0.65 Typ		
F	0.40	0.45	0.425
H	1.80	2.20	2.15
J	0	0.10	0.05
K	0.90	1.00	1.00
L	0.25	0.40	0.30
M	0.10	0.22	0.11
α	0°	8°	-
<b>All Dimensions in mm</b>			

**Package Outline Dimensions**

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Y	0.6
C1	1.9
C2	0.65